



Advanced Technologies for Food Packaging and Preservation

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Message from the Guest Editors

The existing technology for food packaging and preservation has constantly evolved to meet the growing and changing demands of society. Changes in population lifestyle have increased the demand for fresh or minimally processed products and functional, high quality and ready-to-consume foods without traditional preservatives but with a prolonged shelf-life, while also meeting strict food safety regulations. On top of this, there is significant food waste along the supply chain where packaging and conservation technologies are key to significantly reduce these losses. The scientific community is making great efforts to make sustainable, commercially available solutions based on advanced technologies such as active and biodegradable packaging, nanotechnology, irradiation, photocatalysis, 3D printing, high hydrostatic pressures, electric fields or biopreservatives to directly improve food shelf life, while other technologies such as ultrasounds, image analysis, machine learning or other AI applications can be used to monitor food processing and hence improve the overall food quality and safety.

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Message from the Editor-in-Chief

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